

FFM301-CF THRU FFM307-CF

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FFM301-CF THRU FFM307-CF

3.0A Surface Mount Fast Recovery
Rectifiers : 50V ~ 1000V

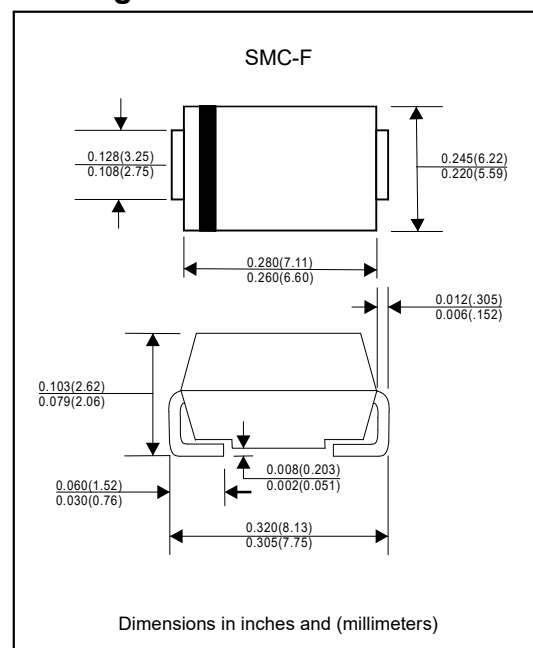
Features

- Idea for printed circuit board.
- Low leakage current.
- High forward surge current capability.
- High temperature soldering guaranteed 250°C/10 seconds at terminals.
- Lead-free parts meet RoHS requirements.
- Suffix "-H" indicates Halogen-free parts, ex. FFM301-CF-H.

Mechanical data

- Epoxy:UL94-V0 rated flame retardant.
- Case : Molded plastic, DO-214AB / SMC-F.
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026.
- Polarity : Indicated by cathode band.
- Mounting Position : Any.
- Weight : Approximated 0.23 grams.

Package outline

Maximum ratings and electrical characteristics (At $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	FFM301 -CF	FFM302 -CF	FFM303 -CF	FFM304 -CF	FFM305 -CF	FFM306 -CF	FFM307 -CF	Unit
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at T _L =100°C	I _(AV)	3							A
Peak forward surge current 8.3ms single half sine wave superimposed on rated load	I _{FSM}	100							A
Maximum instantaneous forward voltage at 3.0A	V _F	1.3							V
Maximum DC reverse current T _A =25°C	I _R	5							μA
at rated DC blocking voltage T _A =125°C		500							
Maximum reverse recovery time (Note 1)	t _{rr}	150				250	500		ns
Typical junction capacitance (Note 2)	C _J	60							pF
Typical thermal resistance	R _{θJA}	47							°C/W
Operating junction temperature	T _J	+150							°C
Storage temperature range	T _{STG}	-55 to +150							°C

Note:

1.Reverse recovery condition $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{rr}=0.25\text{A}$.

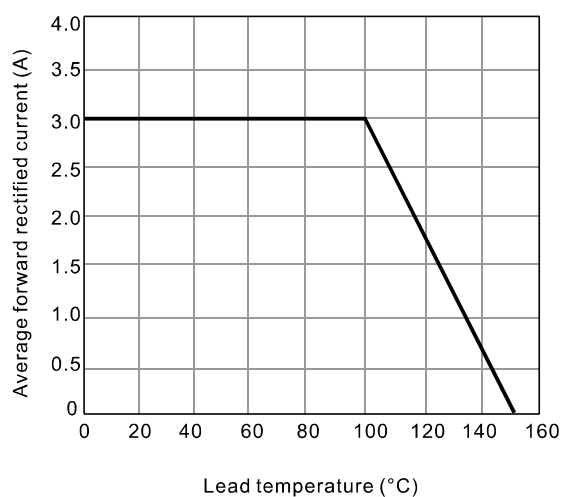
2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

3.Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

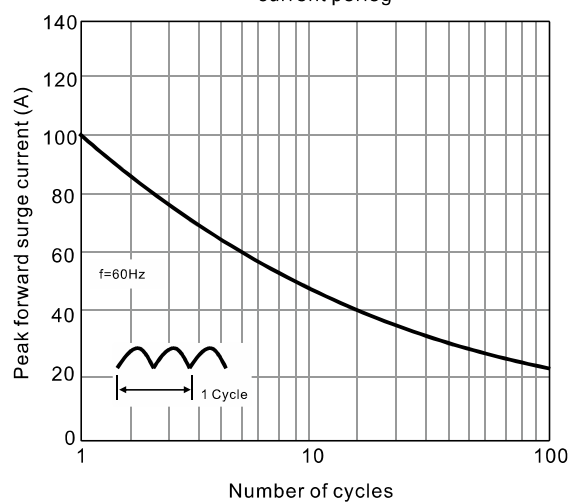
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Rating and characteristic curves

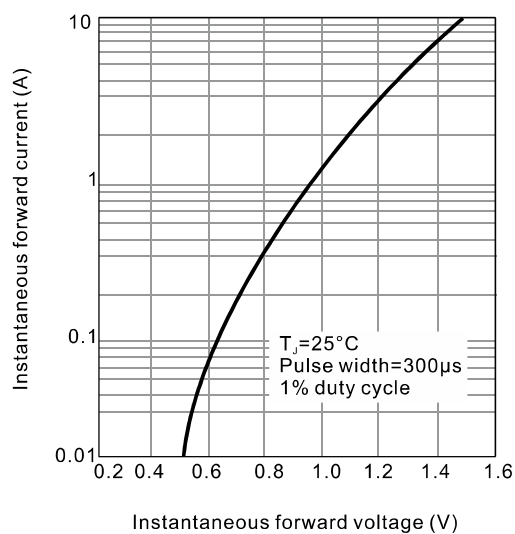
Derating curve output rectified current



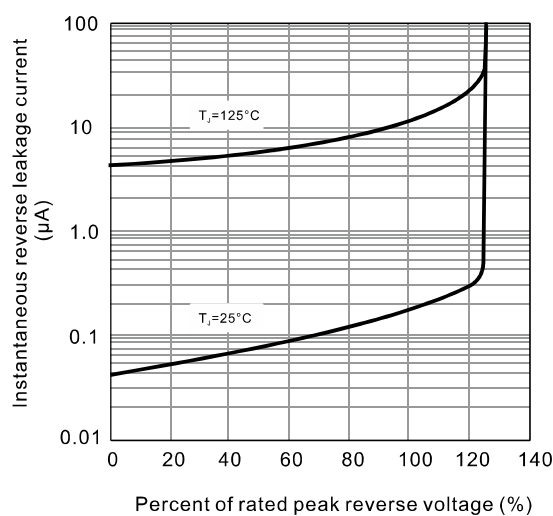
Maximum non-repetitive peak forward surge current per leg



Typical forward voltage characteristics



Typical reverse leakage characteristics

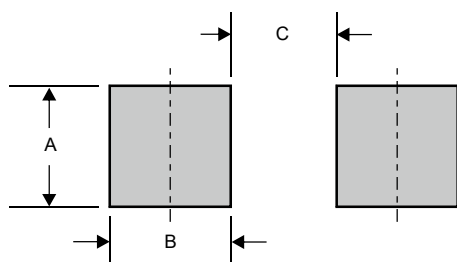


FFM301-CF THRU FFM307-CF**Pinning information**

Pin	Simplified outline	Symbol
Pin1 Cathode Pin2 Anode		

Marking

Type number	Marking code
FFM301-CF	RS3A
FFM302-CF	RS3B
FFM303-CF	RS3D
FFM304-CF	RS3G
FFM305-CF	RS3J
FFM306-CF	RS3K
FFM307-CF	RS3M

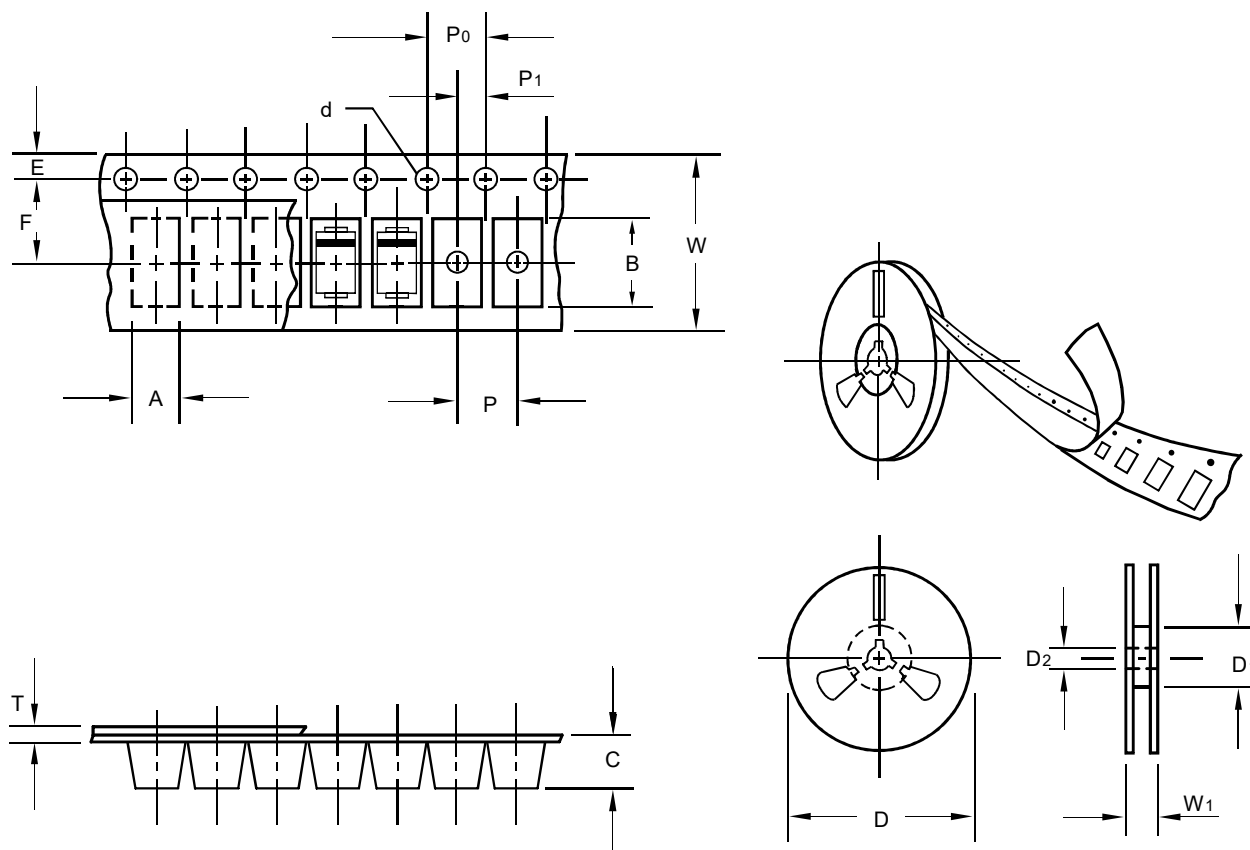
Suggested solder pad layout

Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMC-F	0.130 (3.30)	0.100 (2.50)	0.176(4.40)

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Packing information



unit:mm

Item	Symbol	Tolerance	SMC-F
Carrier width	A	0.15	6.00
Carrier length	B	0.2	8.25
Carrier depth	C	0.1	2.54
Sprocket hole	d	0.1	1.55
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D ₁	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D ₁	min	62.00
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	7.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	16.00
Reel width	W ₁	1.0	18.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

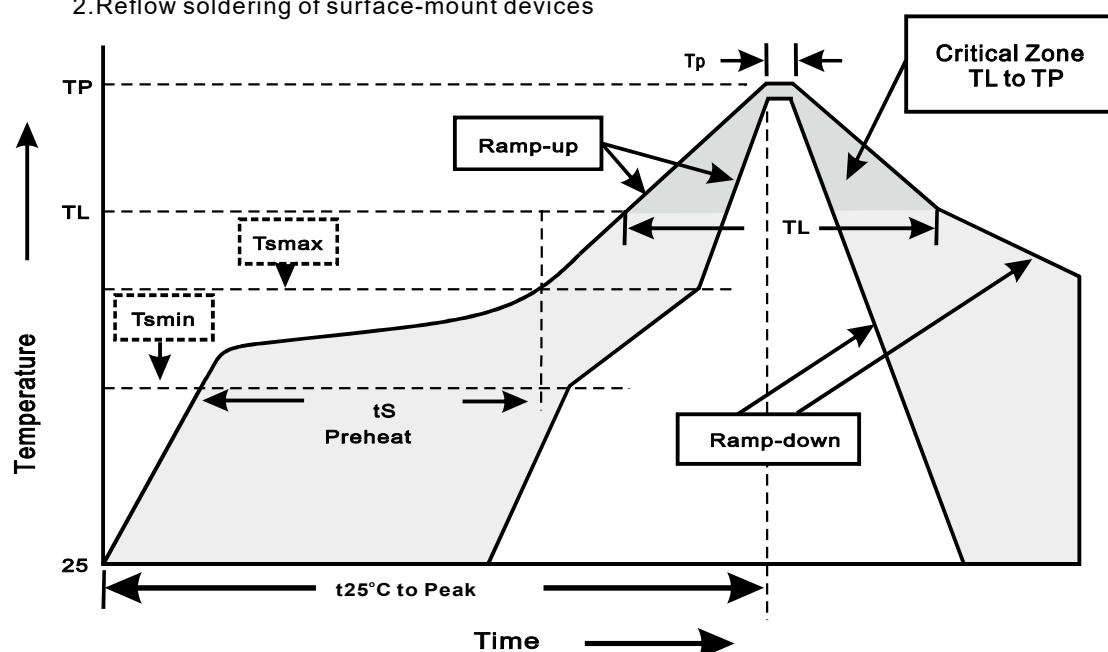
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Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)
SMC-F	13"	3,000	8.0	6,000	338*338*38	330	365*365*360	48,000

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{smin}) -Temperature Max(T _{smax}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{smax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at $260 \pm 5^\circ\text{C}$ for $10 \pm 2\text{sec.}$ immerse body into solder $1/16" \pm 1/32"$	MIL-STD-750D METHOD-2031
2. Solderability	at $245 \pm 5^\circ\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R = 80\%$ rate at $T_J = 125^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A = 25^\circ\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^\circ\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A = 121^\circ\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to $+125^\circ\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Forward Surge	8.3ms single half sine-wave , one surge.	MIL-STD-750D METHOD-4066-2
9. Humidity	at $T_A = 85^\circ\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at 150°C for 1000 hrs.	MIL-STD-750D METHOD-1031